

Momentive's Thermal Interface Materials

Product Guide

Application	Performance Characteristics	Solutions	
Thermal interface in high performance devices and semiconductor packages as TIM1 interfaces or TIM2 thermal paths to heat sinks	- Wide operating temperatures - Repairability - Low thermal resistance - Minimal ionic impurities - Thin bond lines	TIG830SP	4.1 W/m.K
	- Structural adhesion - Minimal ionic impurities - Low thermal resistance - Thin bond lines - Wide operating temperatures	TIG400BX	4.0 W/m.K
Thermal management for optical pick-ups, automotive control units and power supplies	- Low thermal resistance - Room temperature cure	TIG300BX	3.0 W/m.K
	- Non-adhesive, repairable - Low thermal resistance - Room temperature cure	TIG210BX	2.1 W/m.K
Thermal interface with heat dissipation devices in control units, medium performance chip sets etc.	- Moderate thermal conductivity - Wide operating temperatures	TIA600R	6.0 W/m.K
	- Moderate thermal conductivity - Structural adhesion - Low thermal resistance	TIA350R	3.5 W/m.K
Board level and power supply component assembly	- Moderate thermal conductivity - Structural adhesion - Low thermal resistance - Room temperature cure	TIA260R	2.6 W/m.K
		XE13-C1862PT	2.5 W/m.K
Rubber and Gel potting / encapsulation in power modules, converters, IGBT units.	- Moderate thermal conductivity - Structural adhesion - Low thermal resistance - Room temperature cure	TIA0260	2.6 W/m.K
	- Good thermal conductivity - Low ~ moderate viscosities - Stress relief - Handling and cure benefits - Repairability	TIA0220	2.2 W/m.K
		TIS380CM	3.6 W/m.K
		TIS420C	4.2 W/m.K
		TIG1000	1.0 W/m.K
		TIG2000	2.0 W/m.K
		TSE3281-G	1.7 W/m.K
		TSE3280-G	0.9 W/m.K
		TIA0260	2.6 W/m.K
		TIA0220	2.2 W/m.K
		XE11-B5320	1.3 W/m.K
		TIA222G	2.2 W/m.K
		TIA221G	2.1 W/m.K
		TIA216G	1.6 W/m.K